



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20130401002
Qualification of TI Clark as Additional Assembly/Test Site
for DRV8833RTY device
Change Notification / Sample Request**

Date: 4/8/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130401002
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DRV8833RTYT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130401002			PCN Date:	04/08/2013									
Title:	Qualification of TI Clark as Additional Assembly/Test Site for DRV8833RTY device													
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services									
Proposed 1st Ship Date:	07/08/2013	Estimated Sample Availability:	Date Provided at Sample request											
Change Type:														
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials									
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification									
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process									
PCN Details														
Description of Change:														
Qualification of TI Clark as additional assembly and test site for DRV8833RTY device. The device in the product affected list is being qualified by similarity (see Qualification Data).														
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.														
Reason for Change:														
Continuity of Supply														
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):														
None														
Changes to product identification resulting from this PCN:														
<table border="1"> <tr> <td colspan="3">Assembly Site</td> </tr> <tr> <td>TI Malaysia</td> <td>Assembly Site Origin (22L)</td> <td>ASO: MLA</td> </tr> <tr> <td>TI Clark Philippines</td> <td>Assembly Site Origin (22L)</td> <td>ASO: QAB</td> </tr> </table>						Assembly Site			TI Malaysia	Assembly Site Origin (22L)	ASO: MLA	TI Clark Philippines	Assembly Site Origin (22L)	ASO: QAB
Assembly Site														
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA												
TI Clark Philippines	Assembly Site Origin (22L)	ASO: QAB												
Sample product shipping label (not actual product label)														
Device Marking														
<table border="1"> <tr> <td> <div style="border: 1px solid black; padding: 5px; width: 100px; text-align: center;"> O {CUST1} TI YMS LLLL </div> </td> <td> TI = TI LETTERS YM = YEAR MONTH DATE CODE LLLL = ASSEMBLY LOT CODE S = ASSEMBLY SITE CODE O = PIN 1 INDICATOR </td> </tr> </table>						<div style="border: 1px solid black; padding: 5px; width: 100px; text-align: center;"> O {CUST1} TI YMS LLLL </div>	TI = TI LETTERS YM = YEAR MONTH DATE CODE LLLL = ASSEMBLY LOT CODE S = ASSEMBLY SITE CODE O = PIN 1 INDICATOR							
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Topside Device marking:														
Assembly site code for MLA = K														
Assembly site code for TI-Clark = I														

Product Affected:		
DRV8833RTYR	DRV8833RTYT	

Reference Qualification: QFN Package at TI-Clark

Qualification Data: Approved 08/24/2010

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle : TPA2017D2RTJ (MSL 2-260C)

Package Construction Details

Assembly Site:	TI Clark	Mold Compound:	4208625
# Pins-Designator, Family:	20-RTJ, QFN	Mount Compound:	4207768
Leadframe (Finish, Base):	NiPdAu	Bond Wire:	0.96 Mil Dia., Cu

Qualification: ☐ Plan ☒ Test Results

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot3
**High Temp Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**Temp Cycle, -65C/150C	500 Cycles	77/0	77/0	77/0
**Thermal Shock, -65C/150C	500 Cycles	77/0	77/0	77/0
Bond Pull	76 ball bonds, min. 3 units	76/0	76/0	76/0
Bond Shear	76 ball bonds, min. 3 units	76/0	76/0	76/0
Salt Atmosphere	-	22/0	22/0	22/0
Surface Mount Solderability	Pb Free Solder	22/0	22/0	22/0
Manufacturability Qualification (MQ)	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	Level 2-260C	12/0	12/0	12/0
X-ray	(top side only)	5/0	5/0	5/0
**- Preconditioning sequence: Level 2-260C.				

Qual Vehicle 2 : TPS61202DSC (MSL 2-260C)				
Package Construction Details				
Assembly Site:	TI Clark	Mold Compound:	4208625	
# Pins-Designator, Family:	10-DSC, QFN	Mount Compound:	4207768	
Leadframe (Finish, Base):	NiPdAu	Bond Wire:	2.0 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot3
**High Temp Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**Temp Cycle, -65C/150C	500 Cycles	77/0	77/0	77/0
**Thermal Shock, -65C/150C	500 Cycles	77/0	77/0	77/0
Bond Pull	76 ball bonds, min. 3 units	76/0	76/0	76/0
Bond Shear	76 ball bonds, min. 3 units	76/0	76/0	76/0
Salt Atmosphere	-	22/0	22/0	22/0
Surface Mount Solderability	Pb Free Solder	22/0	22/0	22/0
Manufacturability Qualification (MQ)	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	Level 2-260C	12/0	12/0	12/0
X-ray	(top side only)	5/0	5/0	5/0
**- Preconditioning sequence: Level 2-260C.				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com